

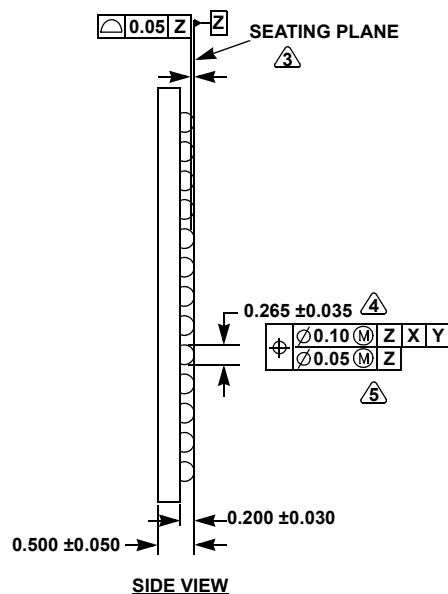
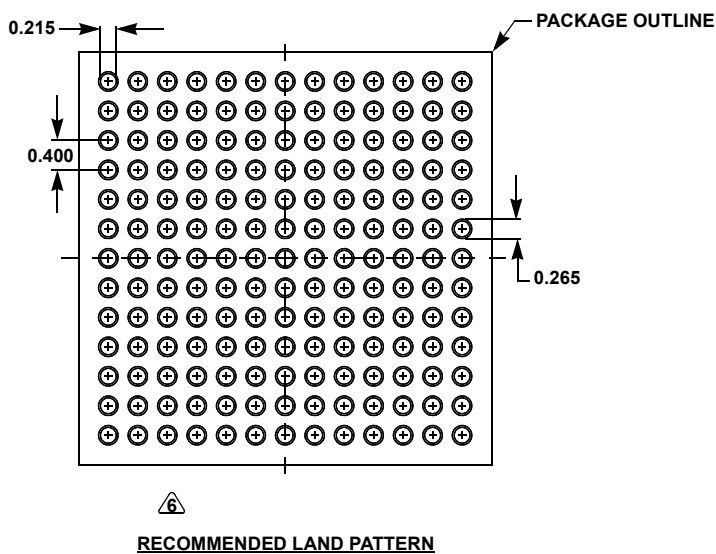
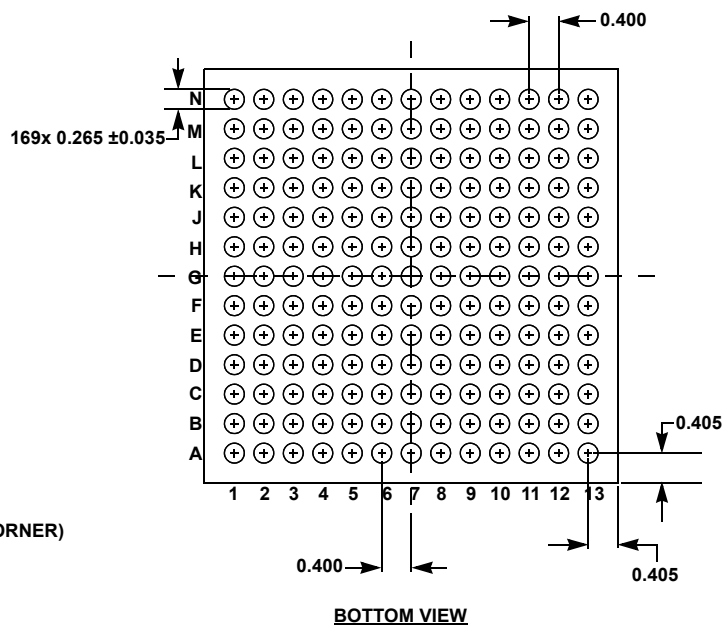
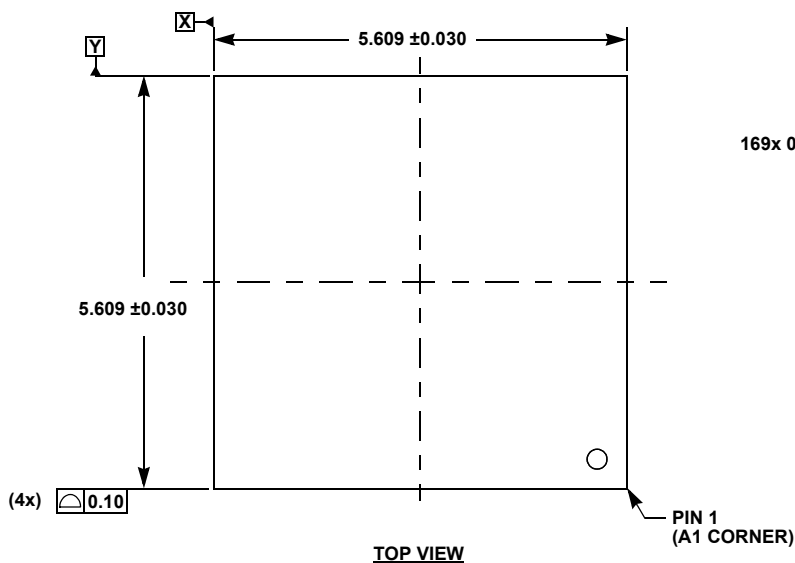
Plastic Packages for Integrated Circuits

Package Outline Drawing

W13x13.169

169 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm pitch)

Rev 1, 9/16



NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerance per ASMEY 14.5-1994.
- Primary datum $\square Z$ and seating plane are defined by the spherical crowns of the bump.
- Dimension is measured at the maximum bump diameter parallel to primary datum $\square Z$.
- Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).